

< *New Market Survey Report* >

Copper Foil Market Report 2022

-by Focusing on the Technology & Market Trends of
Copper Foil for PCB Applications-

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Survey Target Products/Classification **JMS**

*Classification : Copper foil for PCB (ED, RA), Copper Foil for others (Lithium-ion Battery)

*Thickness of Copper Foil for PCB (ED, RA) : 1.5-5um, 6-8um, 9/12um, 18um, 35um, 70um

*Application : Motherboard, IC Package/Module, FPC

*Trends in the focused application fields that are currently gathering attention

<Ultra-thin Copper Foil>

By Thickness : 1.5-less than 2um, 2/3um, 5um, 6-8um

By Application : AiP/AP/Memory IC/SLP/FPC Connector for Antenna Module

<Low Profile Copper Foil>

By Roughness(Rz) : $Rz < 1.0\mu m$, $1.0\mu m \leq Rz < 1.5\mu m$, $1.5\mu m \leq Rz < 2.0\mu m$, $2.0\mu m \leq Rz < 2.5\mu m$

By Application : System, High & Multi-layer PCB, Low-loss CCL

<Copper Foil for FPC>

By Thickness : 6-8um, 12um, 18um, 35um

By Layer Count : 2L FCCL(ED, RA), 3L FCCL(ED, RA)

Survey Target Manufacturers

		Target Manufacturers
Copper Foil Manufacturers	Japan	Mitsui Mining & Smelting Co., Ltd./JX Nippon Mining & Metals Corporation/ Furukawa Electronic Co., Ltd./Fukuda Metal Foil & Power Co., Ltd./ Nippon Denkai, LTD.
	Taiwan	Chang Chun Petrochemical Co., Ltd./NAN YA PLASTICS CORPORATION/ Co-tech Development Corporation/LCY TECHNOLOGY CORPORATION
	China	Kingboard Copper Foil Holdings Ltd./Shenzhen Londian Wason Holdings Group Co., Ltd./Tongling Nonferrous Metals Group Co., Ltd./Nuode Investment Co., Ltd./Jiujiang Defu Technology Co., Ltd./Shandong Jinbao Electronic Co., Ltd./Jiangxi Copper Company Limited/Guangdong Chaohua Technology Co., Ltd.
	Korea	ILJIN Materials Co., Ltd./Solus Advanced Materials Co., Ltd.
CCL Manufacturers		Major Low-loss CCL Manufacturers
PCB Manufacturers		High & Multi-layer PCB Manufacturers, IC Substrate Manufacturers, Communication Module Board Manufacturers, etc.

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